

Power Module Report -2023-

~ Trends in IGBT and SiC power modules ~

Japan Marketing Survey Co., Ltd

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▼ Subjects of survey :

- All IGBT modules including IPM type, and SiC power modules

▼ Companies surveyed

Infineon, Mitsubishi Electric, Fuji Electric, Semikron Danfoss, onsemi, STMicroelectronics, Hitachi Power Semiconductor Device, Rohm, Sanken, Denso, Renesas, Kyocera, Toshiba Electronic Devices & Storage, Wolfspeed, Bosch, Hitachi Energy, Microchip, Vishay, Vincotech, GE, Dynex, Starpower, Macmic, Silvermicro, Silan, BYD Semiconductor, CRRRC Times Semiconductor, Basic

▼ Focal points of survey

- ✓ Market Trends and manufacturer trends of IGBT /SiC power modules
 - Classified by module capacity, by application, by insulating substrate material, by package type
- ✓ The updated comparison tables of product lineup of major 25 module companies
 - Classified by module capacity, by type of circuit, by PKG type, by PM / IPM, of IGBT and SiC modules

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Infineon, Mitsubishi Ele., Fuji Ele., Semikron Danfoss,
onsemi, STMicroelectronics, Wolfspeed, Rohm, Renesas

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